

WEST Search History

DATE: Tuesday, July 29, 2003

<u>Set Name</u> side by side	<u>Query</u>	<u>Hit Count</u>	<u>Set Name</u> result set
<i>DB=USPT,PGPB,JPAB,EPAB,DWPI,TDBD; THES=ASSIGNEE; PLUR=YES; OP=OR</i>			
L33	L32 and (plasma adj1 etching)	3	L33
L32	(metal adj1 substrate adj1 cleaning)	24	L32
L31	l17 same (plasma adj1 etching)	4	L31
L30	surface adj1 treatment adj1 metallic adj1 tube	1	L30
L29	L28 with (plasma adj1 etching)	16	L29
L28	(polymer adj1 substrate)	9187	L28
L27	(polymer adj1 subatrate)	0	L27
L26	L25 same (prior adj1 coating)	2	L26
L25	(plasma adj1 etching) same polymer	1822	L25
L24	L23 and photoresist	39	L24
L23	L22 and coating	80	L23
L22	l19 same (plasma adj1 etching)	140	L22
L21	L20 same (prior adj1 coating)	20	L21
L20	L19 same etching	3802	L20
L19	metal adj1 (substrate or surface)	94827	L19
L18	L17 same etching same (prior adj1 coating)	0	L18
L17	(metal adj1 tube)	28288	L17
L16	L15 same (plasma adj1 etching)	14	L16
L15	stent	15672	L15
L14	l13 same photoresist	33	L14
L13	etching same (prior adj coating)	262	L13
L12	l11 same (prior adj coating)	0	L12
L11	l1 same (metal adj1 substrate)	71	L11
L10	L9	26	L10
L9	l7 and (metal adj substrate)	26	L9
L8	l7 and metal	75	L8
L7	l1 and (prior adj coating) and photoresist	80	L7
L6	l5 and photoresist	3	L6
L5	l3 and metal	16	L5
L4	L3 same tube	0	L4
L3	L2 same (prior adj coating)	20	L3

L3	L2 same (prior adj coating)	20	L3
L2	plasma adj1 etching	28106	L2
L1	plasma adj1 etching	28106	L1

END OF SEARCH HISTORY

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L23: Entry 78 of 80

File: DWPI

Jun 25, 1997

DERWENT-ACC-NO: 1997-322157

DERWENT-WEEK: 200107

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TITLE: Cleaning metal substrate by plasma etching - comprises creating plasma of radicals or ions of hydrogen or inert gas to react with substrate surface negatively biased relatively to anode

INVENTOR: LUCAS, S; VANDEN, B P ; WEYMEERSCH, A ; VANDEN BRANDE, P

PATENT-ASSIGNEE:

ASSIGNEE

CODE

RD-CS RECH & DEV GRP COCKERILL SAMBRE

COCK

PRIORITY-DATA: 1995BE-0001053 (December 20, 1995)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
EP 780485 A1	June 25, 1997	F	010	C23C014/02
ES 2151633 T3	January 1, 2001		000	C23C014/02
BE 1009839 A3	October 7, 1997		015	C23C000/00
EP 780485 B1	August 30, 2000	F	000	C23C014/02
DE 69610064 E	October 5, 2000		000	C23C014/02

DESIGNATED-STATES: AT BE CH DE DK ES FI FR GB GR IE IT LI LU NL PT SE AL AT BE CH DE DK
ES FI FR GB GR IE IT LI LT LU LV NL PT RO SE SI

CITED-DOCUMENTS:2.Jnl.Ref; DD 136047 ; EP 535568

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
EP 780485A1	December 17, 1996	1996EP-0203581	
ES 2151633T3	December 17, 1996	1996EP-0203581	
ES 2151633T3		EP 780485	Based on
BE 1009839A3	December 20, 1995	1995BE-0001053	
EP 780485B1	December 17, 1996	1996EP-0203581	
DE 69610064E	December 17, 1996	1996DE-0610064	
DE 69610064E	December 17, 1996	1996EP-0203581	
DE 69610064E		EP 780485	Based on

INT-CL (IPC): C23 C 0/00; C23 C 14/02; C23 C 16/02; C23 G 5/00

ABSTRACTED-PUB-NO: EP 780485A

BASIC-ABSTRACT:

A metal substrate cleaning process comprises: creating a plasma in a mixture of hydrogen, hydrogen compounds and/or inert gas (e.g. argon) to generate radicals and/or ions for acting on the substrate which is negatively biased with respect to an anode facing the surface to be cleaned. Also claimed is a metal substrate cleaning apparatus, especially for carrying out the above process, comprising devices for generating a plasma and negatively biasing the substrate surface.

USE - Used for metal surfaces, especially steel strips, to enhance adhesion of a subsequent coating, e.g. an electroplated or hot dip coating.

ADVANTAGE - The process eliminates the handling and regeneration problems of pickling solutions, and is carried out continuously at high speed and very efficiently.

ABSTRACTED-PUB-NO:

EP 780485B

EQUIVALENT-ABSTRACTS:

A metal substrate cleaning process comprises: creating a plasma in a mixture of hydrogen, hydrogen compounds and/or inert gas (e.g. argon) to generate radicals and/or ions for acting on the substrate which is negatively biased with respect to an anode facing the surface to be cleaned. Also claimed is a metal substrate cleaning apparatus, especially for carrying out the above process, comprising devices for generating a plasma and negatively biasing the substrate surface.

USE - Used for metal surfaces, especially steel strips, to enhance adhesion of a subsequent coating, e.g. an electroplated or hot dip coating.

ADVANTAGE - The process eliminates the handling and regeneration problems of pickling solutions, and is carried out continuously at high speed and very efficiently.

CHOSEN-DRAWING: Dwg.3/3

TITLE-TERMS: CLEAN METAL SUBSTRATE PLASMA ETCH COMPRISE PLASMA RADICAL ION HYDROGEN INERT GAS REACT SUBSTRATE SURFACE NEGATIVE BIAS RELATIVELY ANODE

DERWENT-CLASS: M12 M14 X25

CPI-CODES: M12-A05; M14-A;

EPI-CODES: X25-A04;

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C1997-104256

Non-CPI Secondary Accession Numbers: N1997-266538